

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"US 20070099129"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2008/02/16 10:36
L2	4	jp-07239558-\$.did. or jp-06275514-\$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:48
L3	103546	develop\$3 with (wafer or substrate)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:51
L4	3389	develop\$3 near2 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:52
L5	14388	(wash\$3 or rins\$3) near2 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:52
L6	3152	(chemical or curing) near2 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55
L7	1016	3 and 4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55
L8	243	7 and 5	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55
L9	10	8 and 6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55

L10	702	(adjuvant or curing) near3 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:04
L11	28	3 and 10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:05
L12	73	curing with \$5resist with (remain\$3 or residual) with develop \$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:12
L13	2	4 and 12	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:16
L14	6	(355/27.ccls. or 396/611.ccls. or 430/5,30.ccls.) and 12	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:17
L15	7	liquid with curing with \$5resist with (remain\$3 or residual) with develop \$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:21
L16	114	liquid near3 curing with \$5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:28
L17	21	3 and 16	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:28
L18	128995	develop\$4 with (wafer or substrate)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:29
L20	25	16 and 18	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:29

L21	4	curing with \$5resist with (remain\$3 or residual) with develop \$4 same (solvent or liquid or solution) near2 cur\$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:36
L22	99	cur\$3 with \$5resist with develop\$4 same (solvent or liquid or solution) near2 cur\$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:38
L23	11	cur\$3 with \$5resist with developed near2 (\$5resist or wafer or substrate) same (solvent or liquid or solution) near2 cur\$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:46

2/16/08 11:49:14 AM